

I Claim:

1. A method including the steps of:

- a) providing a sheet of thermoplastic material;
- b) providing an upper and a lower mold for molding the sheet;
- 5 c) sandwiching the sheet between the upper and lower molds;
- d) heating the sheet, and
- e) urging the upper and lower molds together to deform the sheet to form the array of caps,

wherein the array of caps is for attachment to a wafer which includes a plurality of micro
10 fabricated devices.

2. The method of claim 1 wherein step e) results in deformation of the sheet and the material of the sheet is substantially reduced in thickness or substantially removed in regions between the caps so formed.

3. The method of claim 1 wherein after step e) the array is subject to an etch to remove any extraneous material between the caps.

4. The method of claim 1 wherein step e) results in deformation of the sheet but the sheet remains substantially the same thickness.

5. The method of claim 1 wherein step a) includes providing a sheet which absorbs electromagnetic radiation at one or more wavelengths.

6. The method of claim 1 wherein the sheet absorbs radiation within the wavelength range of about 1000 nm to about 5000 nm.

7. The method of claim 1 wherein step b) includes providing at least one mold at least partially transparent or translucent to the electromagnetic radiation at said one or more wavelengths.

8. The method of claim 1 wherein step d) includes irradiating the sheet with electromagnetic radiation at one or more wavelengths.

9. The method of claim 1 wherein step d) includes irradiating the sheet with infrared radiation.

10. The method of claim 1 wherein step b) includes providing molds formed of a

5 semiconductor material.

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